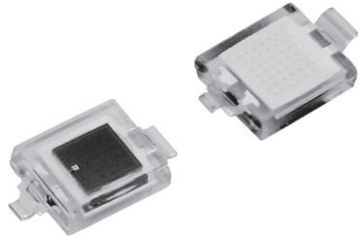
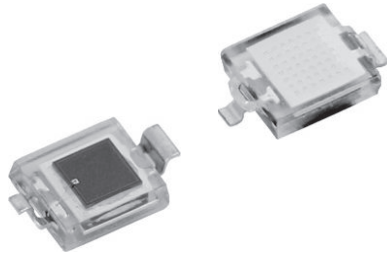




Silicon PIN Photodiode



VBP104S



VBP104SR

FEATURES

- Package type: surface mount
- Package form: GW, RGW
- Dimensions (L x W x H in mm): 6.4 x 3.9 x 1.2
- Radiant sensitive area (in mm²): 4.4
- High photo sensitivity
- High radiant sensitivity
- Suitable for visible and near infrared radiation
- Fast response times
- Angle of half sensitivity: $\varphi = \pm 65^\circ$
- Floor life: 168 h, MSL 3, acc. J-STD-020
- Lead (Pb)-free reflow soldering
- Compliant to RoHS Directive 2002/95/EC and in accordance to WEEE 2002/96/EC
- Halogen-free according to IEC 61249-2-21 definition



DESCRIPTION

VBP104S and VBP104SR are high speed and high sensitive PIN photodiodes. It is a surface mount device (SMD) including the chip with a 4.4 mm² sensitive area detecting visible and near infrared radiation.

APPLICATIONS

- High speed photo detector

| PRODUCT SUMMARY | | | |
|-----------------|----------------------|---------|-----------------------|
| COMPONENT | I _{ra} (μA) | φ (deg) | λ _{0.1} (nm) |
| VBP104S | 35 | ± 65 | 430 to 1100 |
| VBP104SR | 35 | ± 65 | 430 to 1100 |

Note

- Test conditions see table “Basic Characteristics”

| ORDERING INFORMATION | | | |
|----------------------|---------------|------------------------------|------------------|
| ORDERING CODE | PACKAGING | REMARKS | PACKAGE FORM |
| VBP104S | Tape and reel | MOQ: 1000 pcs, 1000 pcs/reel | Gullwing |
| VBP104SR | Tape and reel | MOQ: 1000 pcs, 1000 pcs/reel | Reverse gullwing |

Note

- MOQ: minimum order quantity

| ABSOLUTE MAXIMUM RATINGS (T _{amb} = 25 °C, unless otherwise specified) | | | | |
|---------------------------------------------------------------------------------|-----------------------------------|-------------------|---------------|------|
| PARAMETER | TEST CONDITION | SYMBOL | VALUE | UNIT |
| Reverse voltage | | V _R | 60 | V |
| Power dissipation | T _{amb} ≤ 25 °C | P _V | 215 | mW |
| Junction temperature | | T _j | 100 | °C |
| Operating temperature range | | T _{amb} | - 40 to + 100 | °C |
| Storage temperature range | | T _{stg} | - 40 to + 100 | °C |
| Soldering temperature | Acc. reflow solder profile fig. 8 | T _{sd} | 260 | °C |
| Thermal resistance junction/ambient | | R _{thJA} | 350 | K/W |

| BASIC CHARACTERISTICS ($T_{amb} = 25\text{ }^{\circ}\text{C}$, unless otherwise specified) | | | | | | |
|-----------------------------------------------------------------------------------------------------|-------------------------------------------------------------------------------|-----------------|------|---------------------|------|-----------------------------|
| PARAMETER | TEST CONDITION | SYMBOL | MIN. | TYP. | MAX. | UNIT |
| Forward voltage | $I_F = 50\text{ mA}$ | V_F | | 1 | 1.3 | V |
| Breakdown voltage | $I_R = 100\text{ }\mu\text{A}$, $E = 0$ | $V_{(BR)}$ | 60 | | | V |
| Reverse dark current | $V_R = 10\text{ V}$, $E = 0$ | I_{ro} | | 2 | 30 | nA |
| Diode capacitance | $V_R = 0\text{ V}$, $f = 1\text{ MHz}$, $E = 0$ | C_D | | 48 | | pF |
| | $V_R = 3\text{ V}$, $f = 1\text{ MHz}$, $E = 0$ | C_D | | 17 | 40 | pF |
| Open circuit voltage | $E_e = 1\text{ mW/cm}^2$, $\lambda = 950\text{ nm}$ | V_o | | 350 | | mV |
| Temperature coefficient of V_o | $E_e = 1\text{ mW/cm}^2$, $\lambda = 950\text{ nm}$ | TK_{V_o} | | -2.6 | | mV/K |
| Short circuit current | $E_e = 1\text{ mW/cm}^2$, $\lambda = 950\text{ nm}$ | I_k | | 32 | | μA |
| Temperature coefficient of I_k | $E_e = 1\text{ mW/cm}^2$, $\lambda = 950\text{ nm}$ | TK_{I_k} | | 0.1 | | %/K |
| Reverse light current | $E_e = 1\text{ mW/cm}^2$, $\lambda = 950\text{ nm}$, $V_R = 5\text{ V}$ | I_{ra} | 25 | 35 | | μA |
| Angle of half sensitivity | | ϕ | | ± 65 | | deg |
| Wavelength of peak sensitivity | | λ_p | | 940 | | nm |
| Range of spectral bandwidth | | $\lambda_{0.1}$ | | 430 to 1100 | | nm |
| Noise equivalent power | $V_R = 10\text{ V}$, $\lambda = 950\text{ nm}$ | NEP | | 4×10^{-14} | | $\text{W}/\sqrt{\text{Hz}}$ |
| Rise time | $V_R = 10\text{ V}$, $R_L = 1\text{ k}\Omega$, $\lambda = 820\text{ nm}$ | t_r | | 100 | | ns |
| Fall time | $V_R = 10\text{ V}$, $R_L = 1\text{ k}\Omega$, $\lambda = 820\text{ nm}$ | t_f | | 100 | | ns |

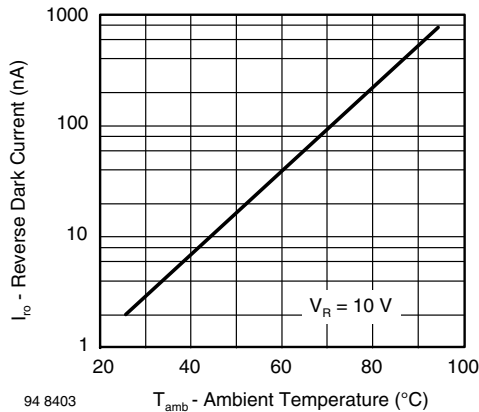
BASIC CHARACTERISTICS ($T_{amb} = 25\text{ }^{\circ}\text{C}$, unless otherwise specified)


Fig. 1 - Reverse Dark Current vs. Ambient Temperature

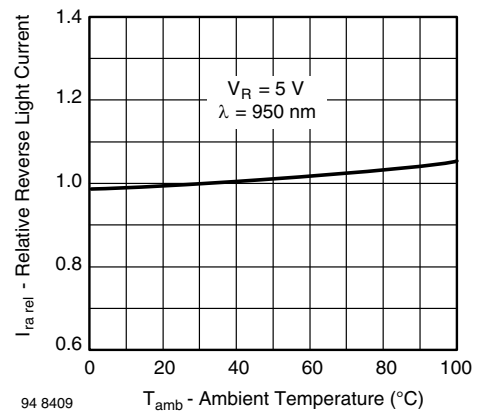


Fig. 2 - Relative Reverse Light Current vs. Ambient Temperature

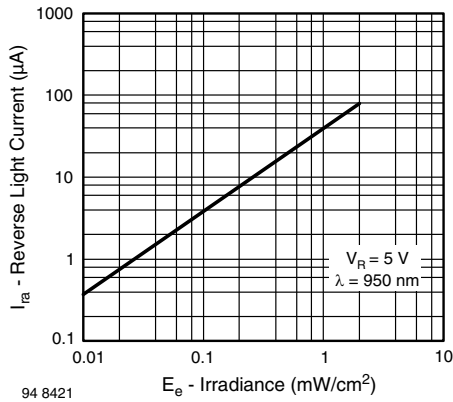


Fig. 3 - Reverse Light Current vs. Irradiance

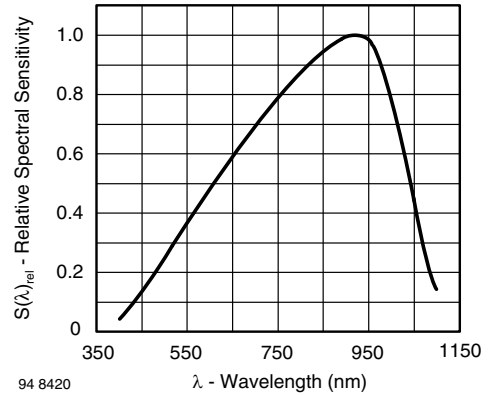


Fig. 6 - Relative Spectral Sensitivity vs. Wavelength

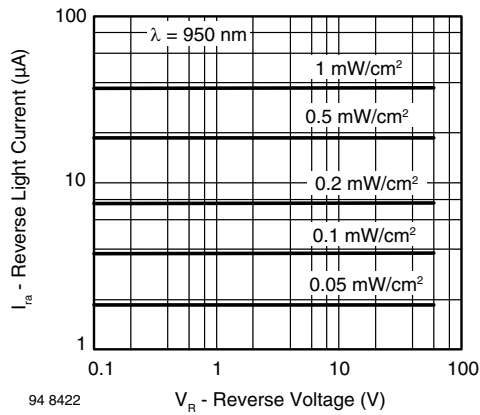


Fig. 4 - Reverse Light Current vs. Reverse Voltage

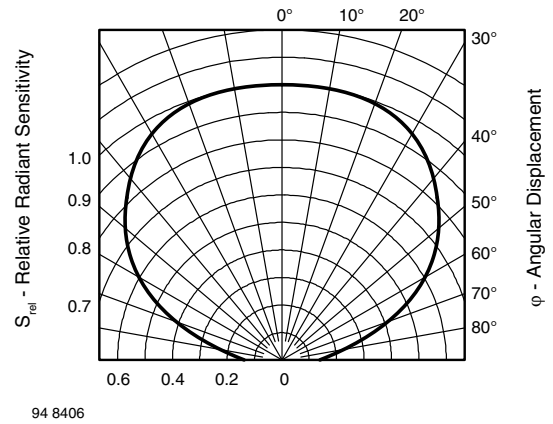


Fig. 7 - Relative Radiant Sensitivity vs. Angular Displacement

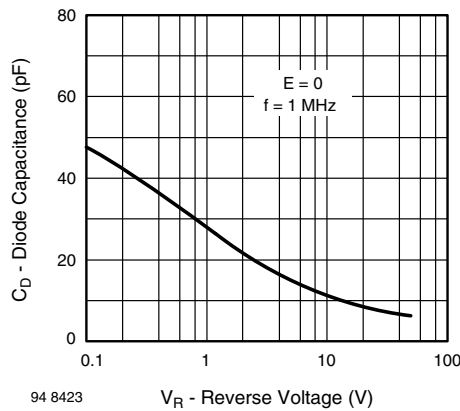
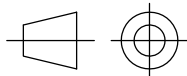
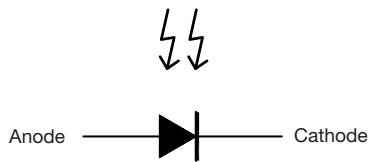
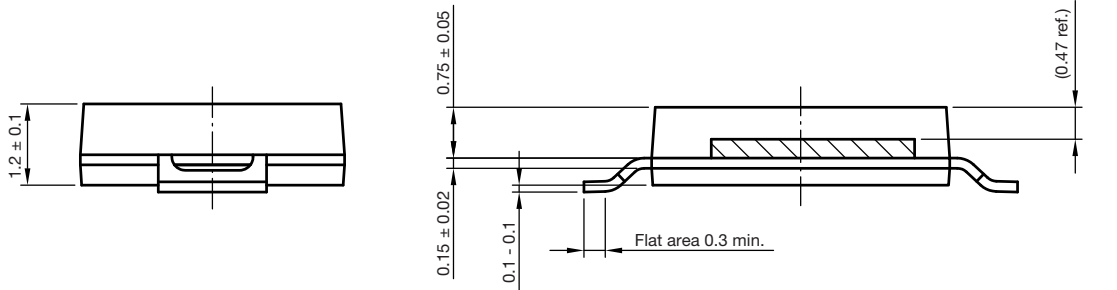


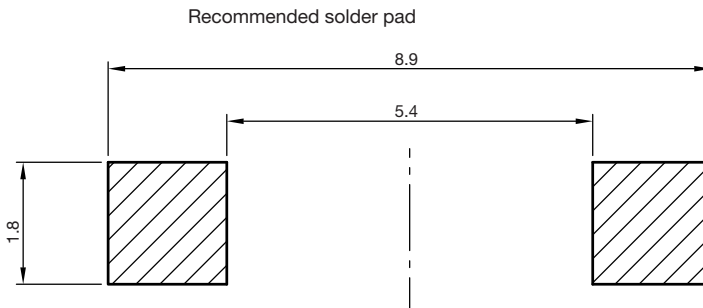
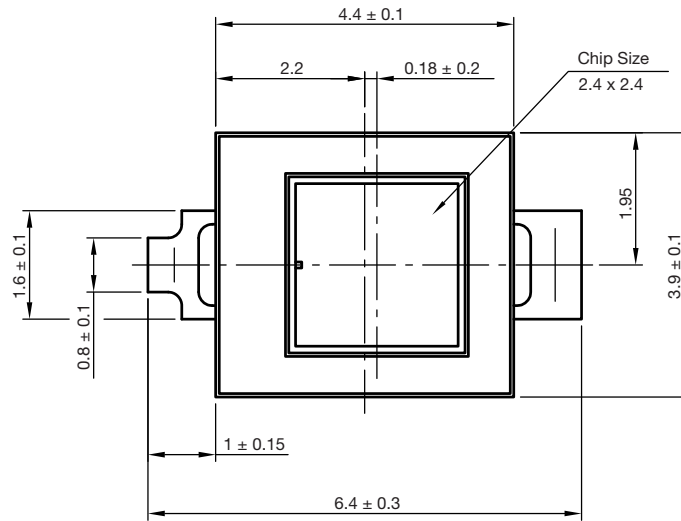
Fig. 5 - Diode Capacitance vs. Reverse Voltage



PACKAGE DIMENSIONS FOR VBP104S in millimeters



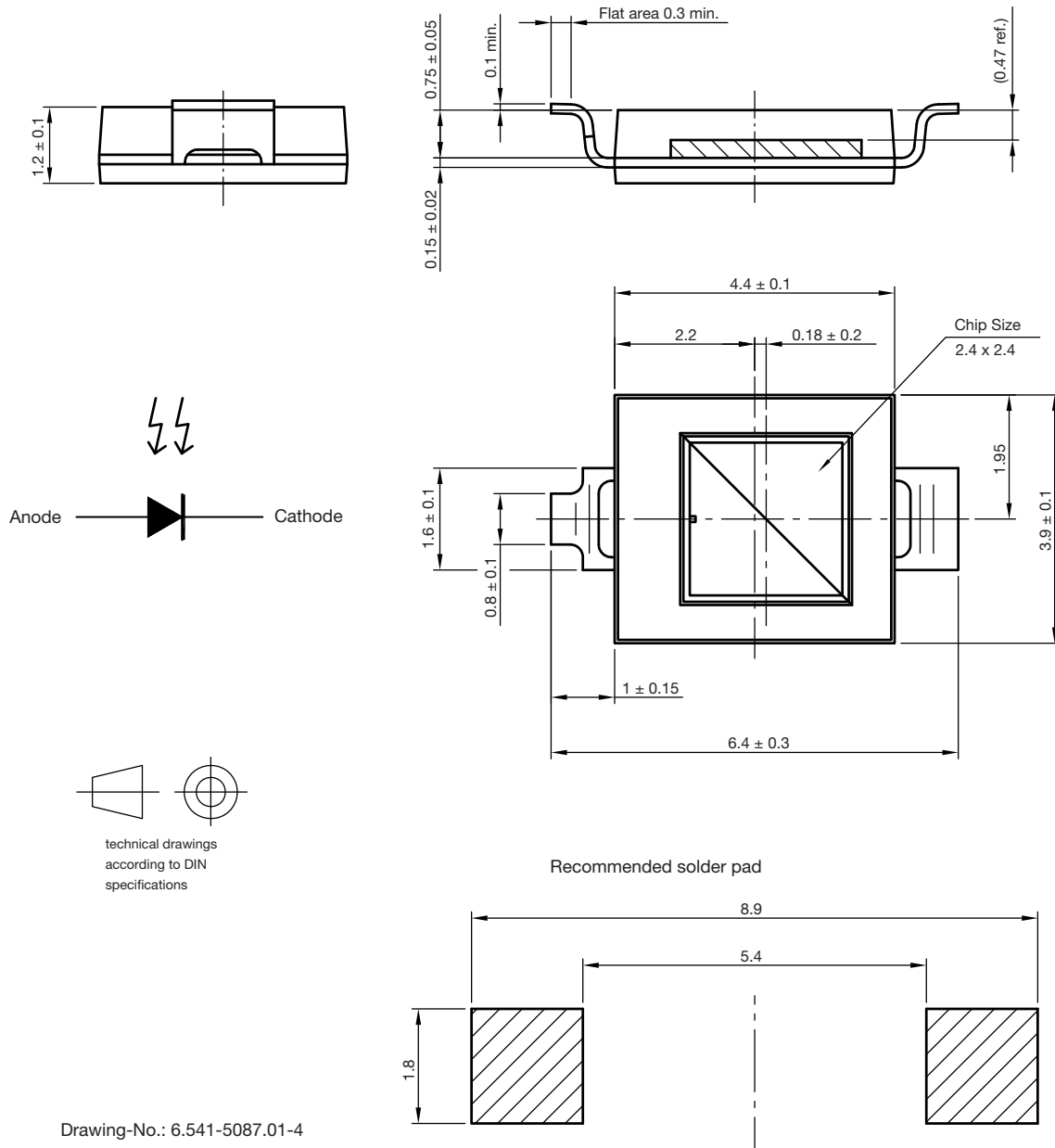
technical drawings according to DIN specifications



Drawing-No.: 6.541-5088.01-4
Issue: 1; 15.04.10
22107



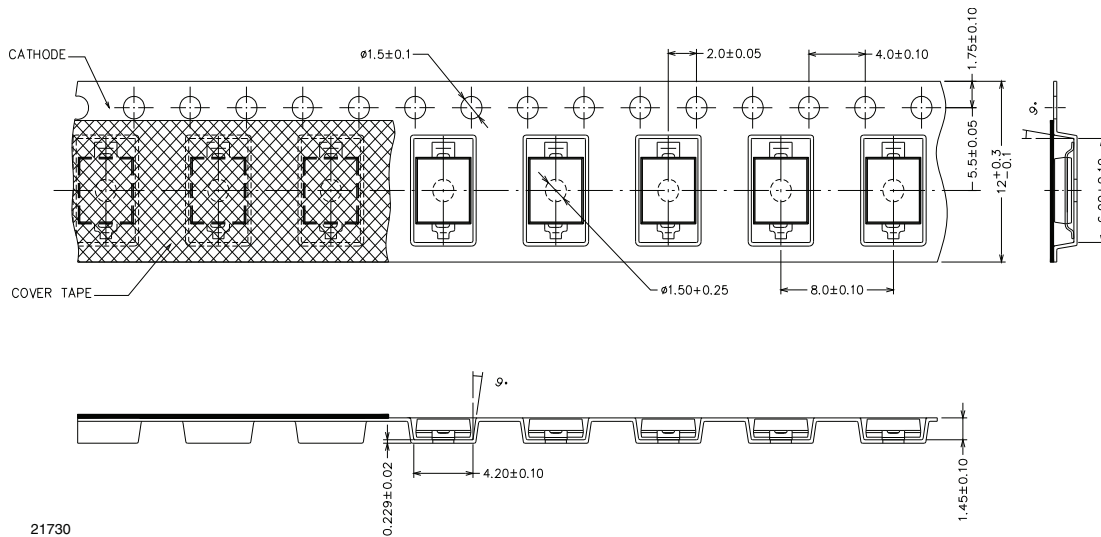
PACKAGE DIMENSIONS FOR VBP104SR in millimeters



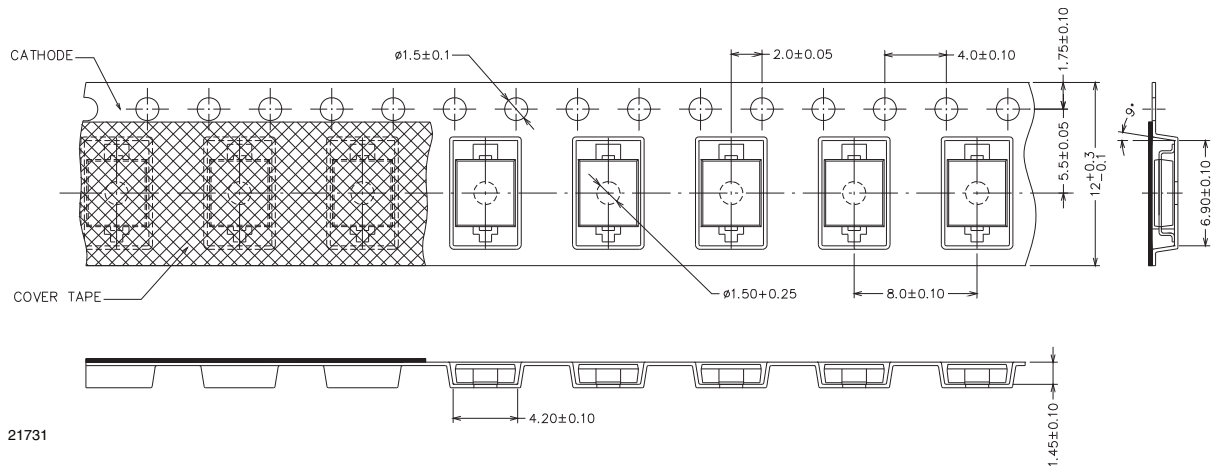
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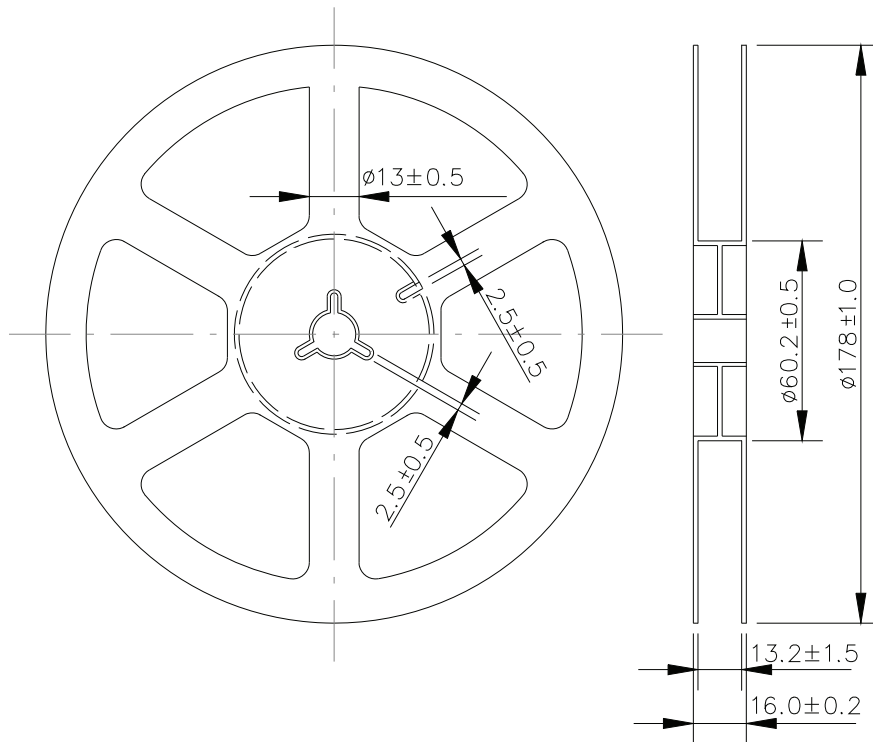
TAPING DIMENSIONS FOR VBP104S in millimeters



TAPING DIMENSIONS FOR VBP104SR in millimeters

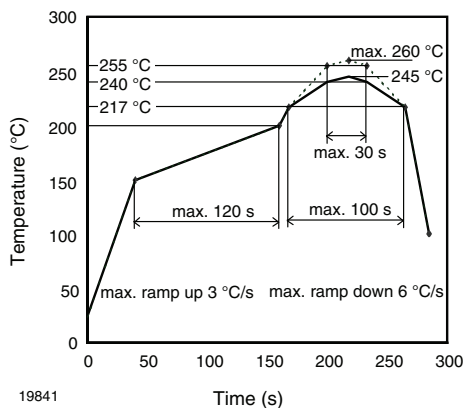


REEL DIMENSIONS FOR VBP104S AND VBP104SR in millimeters



21732

SOLDER PROFILE



19841

Fig. 8 - Lead (Pb)-free Reflow Solder Profile acc. J-STD-020

DRYPACK

Devices are packed in moisture barrier bags (MBB) to prevent the products from moisture absorption during transportation and storage. Each bag contains a desiccant.

FLOOR LIFE

Time between soldering and removing from MBB must not exceed the time indicated in J-STD-020:

Moisture sensitivity: level 3

Floor life: 168 h

Conditions: $T_{amb} < 30\text{ }^{\circ}\text{C}$, RH < 60 %

DRYING

In case of moisture absorption devices should be baked before soldering. Conditions see J-STD-020 or recommended conditions:

192 h at 40 °C (+ 5 °C), RH < 5 %

or

96 h at 60 °C (+ 5 °C), RH < 5 %.



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